TC5090AP

TC5090AP PENTAPHASIC INTEGRATION 8-BIT A/D CONVERTER

The TC5090AP is a pentaphase integration 8-bit A/D converter of high precision and low power consumption, which is mounted in a compact 16-pin standard package. The 8-bit output data can be taken out in the form of time-shared higher order 4 bits and lower order 4 bits on four 3-state data outputs.

This output system is designed specifically considering interface to 4-bit CPU.

The features of low power consumption and compact outline are applicable to battery-driven small-sized instruments.

FEATURES:

- . High precision : ±1 LSB MAX.
- . High precision : II LSB MAX.

 . Low power consumption: 10mW(Typ.) @ (VDD=5V)

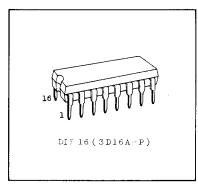
 Citals across county . VDD=5+1 5V fosc=1MHz) . Single power supply : VDD=5±1.5V
- . High-speed conversion: 2mS(Max.) @fosc=1.5MHz
- . Reference clock oscillation circuit contained (CR oscillation)
- . 3-state output with output latch
- . TTL/CMOS compatible digital Input/Output
- . Offset automatic correction

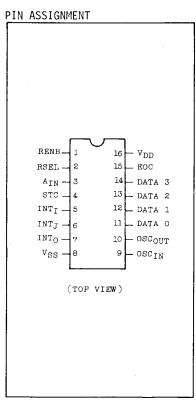
APPLICATIONS:

- . Various control instruments (for temperature, humidity, pressure, etc.)
- . Home electric appliances
- . Electric wiring apparatuses
- . Battery-driven instruments

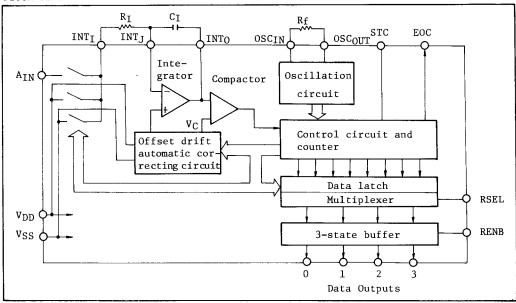
ABSOLUTE MAXIMUM RATINGS

CHARACTERISTIC	SYMBOL	RATING	UNIT
DC Supply Voltage	v_{DD}	V _{SS} -0.5 ~ V _{SS} +8	V
Input Voltage	v_{IN}	$V_{SS}-0.5 \sim V_{DD}+0.5$	v
Output Voltage	VOUT	$V_{SS}-0.5 \sim V_{DD}+0.5$	V
DC Input Current	IIN	±10	mA
Power Dissipation	$P_{\mathbf{D}}$	300	mW
Operating Temperature Range	Topr	-40 ~ 85	°c
Storage Temperature Range	Tstg	- 65 ~ 150	°C

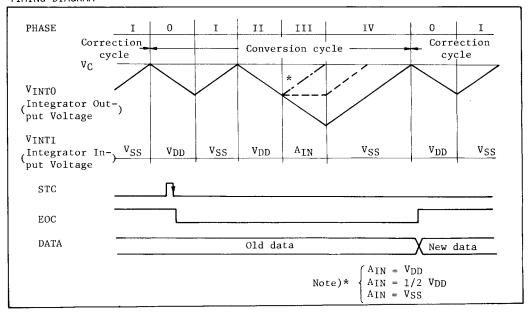




BLOCK DIAGRAM



TIMING DIAGRAM



FUNCTION OF EACH PIN

PIN NO.	SYMBOL	NAME & FUNCTION	PIN NO.	SYMBOL	NAME & FUNCTION
		(Read Enable) Data read signal.		OSC IN	I/O for reference clock oscillation. Clock oscillation can be made by means of external
1 RENB		"H": The data 0 ∿ 3 can be output. "L": The output above is at high impedance.		OSC OUT	registance. Clock can be sup- plied from outside through
		(Read Select) Input to select the higher	11	DATA O	(2 t b Develled Date Outents)
		order 4 bits or the lower	12	DATA 1	(3-state Parallel Data Outputs)
2	RSEL	order 4 bits to 4-bit data output.	13	DATA 2	Conversion data output. The data 0 is LSB, and the
	"H": Output of the higher order 4 bits. "L": Output of the lower order 4 bits.		14	DATA 3	data 3 is MSB.
3	AIN	(Analog Input) $ \label{eq:Analog Input} $ Analog input terminals. $ \label{eq:Input Voltage range is VDD} \sim V_{SS}. $		EOC	(End of Conversion) Conversion ending signal. EOC goes to "L" level at the fall of STC, and returns to "H" level at the end of
4 STC		(Start Conversion) Conversion starting signal. Conversion starts at the fall- ing edge.		Loc	conversion.
5	INT I	(Integrator Input, Integrator Junction, Integrator Output)			
6	INT J	Integrator consists of external resistor $R_{\rm I}$ and external capacitor $C_{\rm I}$.			(Power Supply) 5V±1.5V
7	INT O			v _{DD}	
8	V _{SS}	(Ground) Normally OV			·

FUNCTIONAL DESCRIPTION

(1) System Description (Pentaphasic Integration)

The operation of the TC5090AP is composed of the correction cycle and the conversion cycle as shown in the timing chart. While the power is switched on, the repetition of correction cycle and conversion cycle enables the TC5090AP at make A/D conversion under the optimum conditions at all times. The operation flowchart is shown in Fig. 1.

(a) Initial correction period

The internal state of this LSI is reasonably unsettled at the time when the power is switched on;

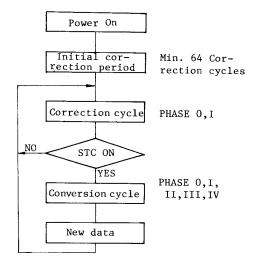


Fig. 1 Operation Flowchart

therefore, the initial correction cycle is requires before stable converting operation becomes possible.

The correction cycle automatically corrects conversion error caused by offset voltage of the integrator or the like, and is composed of the period (PHASE 0) for which VDD is integrated and the period (PHASE 1) for which $V_{\rm SS}$ is integrated.

Since system correction is performed in steps at the end of this PHASE I, 64 correction cycles (64 \times 1024 \cdot T $_{OSC}$) are required as the initial correction period. (Tosc denotes one clock cycle.)

(b) Conversion cycle

If the initial corection cycle period is completed, normal conversion becomes possible.

When STC input is given, (although the correction cycle in PHASE O or PHASE I is in operation at this time), the correction operation stops, and the conversion cycle starts.

In other words, even if STC input is given, this LSI performs the same operation as the correction cycle until PHASE I is completed; but it does not perform the correction at the time of completion of PHASE I, and shifts to PHASE II. Therefore, attention should be given to the fact that PHASE I prior to PHASE II does not act as correction cycle.

When STC input is given, the LSI integrates analog input in PHASE III through PHASE I and PHASE II, performing digital conversion in PHASE IV. When the LSI completes digital conversion in PHASE IV, the output is turned to the new data and the LSI returns to the correction cycle.

(c) Correction cycle

When the next STC input is given between completion of arbitrary conversion cycle (at the time of completion of PHASE IV) and completion of one correction cycle (1024·ToSC), no correction is substantially made. Therefore, in case the STC input is consecutively given, another STC should be given after the lapse of one correction cycle at the earliest from completion of PHASE IV. When the STC input is given during conversion (while EOC is at "L" level), the STC cannot be accepted.

(d) Constant of integration

The $\ensuremath{R_{\mathrm{I}}}$ and $\ensuremath{C_{\mathrm{I}}}$ composing the integrator should be selected to satisfy the following equation.

$$R_{\rm I}C_{\rm I} = (0.9 \, ^{\circ}2.5) \, \cdot \, \frac{103}{{
m fosc}} \, [S]$$

Attention should be paid to the fact that, when the external R oscillation is used, $f_{\rm OSC}$ has $\pm 30\%$ variations in regard to the typ. value in Fig. 5 due to variations in sample and temperature characteristic.

In other words, if the typ. value in Fig. 5 is denoted by f_{R} . TYP, the $R_{\rm I}$ and $C_{\rm I}$ should be selected according to the following equation.

$$R_{I}C_{I} = (1.2 \cdot 1.75) \cdot \frac{10^{3}}{f_{R \cdot TYP}}$$
 [S]

(2) Output Data Mode

TRUTH TABLE

		. DIGITAL OUTPUTS								
RENB	ANALOG INPUT		RSEL				RSEL = "H"			
		DATA	DATA		DATA	DATA	DATA	DATA	DATA	
		0	1	2	3	0	1	2	3	
L	Don't care				High :	Impeda	nce			
Н	$<\frac{1}{2}$ LSB	L	L	L	L	L	L	L	L	
Н	$-\frac{1}{2}$ LSB $\sim \frac{1}{2}$ LSB	L	L	L	L	L	L	L	L	
Н	$\frac{1}{2}$ LSB $\sim \frac{3}{2}$ LSB	Н	L	L	L	L	L	L	L	
Н			Straight Binary					L		
Н	"FS" $-\frac{5}{2}$ LSB \sim "FS" $-\frac{3}{2}$ LSB	L	Н	Н	Н	Н	Н	Н	Н	
Н	"FS"- $\frac{3}{2}$ LSB \sim "FS"- $\frac{1}{2}$ LSB	Н	Н	н	н	Н	Н	Н	Н	
Н	"FS"- $\frac{1}{2}$ LSB <	Н	Н	Н	Н	Н	н	Н	Н	

Note :
$$V_{SS} = 0V$$

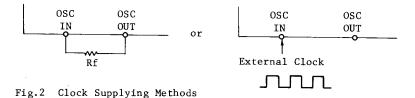
1 LSB =
$$V_{DD}/256$$

"FS" Full Scale (
$$V_{\mathrm{DD}}$$
)

8-bit digital data is output on four data lines after having been divided into the higher order 4 bits and the lower order 4 bits. Either the higher order bits or the lower order bits can be selected by RSEL.

(3) .System Clock Oscillation Circuit

For oscillating reference clock the oscillation circuit is composed of external resistors as shown in Fig. 2.



(4) Timings for STC-EOC and EOC-DATA

o Time (tSE) from the fall of STC to the fall of EOC.

$$t_{SE} = \frac{1}{2} T_{OSC} \sim \frac{3}{2} T_{OSC}$$

o Time (tpE) from the out of DATA output to the rise of EOC

$$t_{DE} = \frac{1}{2} T_{OSC}$$

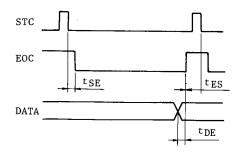


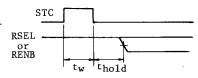
Fig. 3 Timing chart of STC/EOC

o Min. time ($t_{\mbox{ES}}$) from the rise of EOC to the acceptance of another STC.

$$t_{ES} = \frac{1}{2} T_{OSC} \sim \frac{3}{2} T_{OSC}$$

(5) Timings for STC Input and RSEL/RENB Input

STC signal is taken in synchronously with the internal clock; therefore, if TOSC denotes one clock cycle of OSC terminal, the pulse width of more than $(2 \cdot T_{OSC})$ is required.



Either RSEL input or RENB input is required to be set to "H" level at the falling time of STC by reason of internal structure.

Fig.4 Timing chart of Control Input

Further, the hold time of $(T_{OSC} + 50ns)$ or more after the falling time of STC at least for "H" level time of RSEL or REMB is required.

NOTE:
$$t_w > 2 \cdot T_{OSC}$$
, $t_{hold} > T_{OSC} + 50 \text{ns}$

RECOMMENDED OPERATING CONDITIONS (Vss = ov)

ITEM	SYMBOL		MIN.	TYP.	MAX.	UNIT
Supply Voltage	V _{DD}		3.5	5	6.5	v
Input Voltage	VIN		0	-	VDD	v
Integral Resistor	RI		0.4	.	2	MΩ
Integral Capacitor	CI			Note		
Oscillatory Resistance	Rf	$V_{DD} = 5V$	10	_		kΩ

Note: Refer to Fuction Description (1) for determing the values of $R_{\rm I}$ and $C_{\rm I}$, respectively.

ELECTRICAL CHARACTERISTICS ($V_{SS} = 0V$)

ITEM	SYM-	TEST	$v_{ m DD}$	-4	0°C				85°C		UNIT
*****	BOL	CONDITIONS	[V]	MIN.	MAX.			MAX.	O.T.I		
Input High Voltage	v _{OH}	IOUT <1 µA VIN=VSS, VDD	5	4.95	_	4.95	5.00		4.95	_	v
Output Low Voltage	VOL	IOUT <1µA VIN=VSS, VDD	5	-	0.05	_	0.00	0.05	-	0.05	
Output High Current	IOH	V _{OH} =4.0V * V _{IN} =V _{SS} ,V _{DD}	5	-1.2	-	-1.0	-2.0	-	-0.7	-	mA
Output Low Current	I _{OL}	V _{OL} =0.4V * V _{IN} =V _{SS} ,V _{DD}	5	2.4	-	2.0	4.0	-	1.6	_	
Input High Voltage	ν _{IH}	*	5	2.4	_	2.4	-	_	2.4	_	v
Input Low Voltage	VIL	*	5	-	0.8	-	_	0.8	-	0.8	V
Output Disable Current	IDH	VOH=6.5V *	6.5	-	±0.5	-	±10-4	±0.5	-	± 5	
Input Current	IIH	V _{IH} =6.5V * V _{IL} =0V	6.5	-	<u>+</u> 0.3	_	±10 ⁻⁵	±0.3	-	<u>+</u> 1	μА
Analog Switch Off- Leak Current	IOFF	I _{IH} =6.5V V _{IL} =0V	6.5	-	±0.3	-	±10 ⁻⁵	±0.3	-	<u>+</u> 1	
Operating Con- sumption Current	IDD (opr)	fosc = 1 MHz	5	-	-	-	2.0	3	_	_	mA

 $[\]star$ Applicable to digital input/output. Not applicable to analog input/output and ${\tt OSCIN/OSCOUT.}$

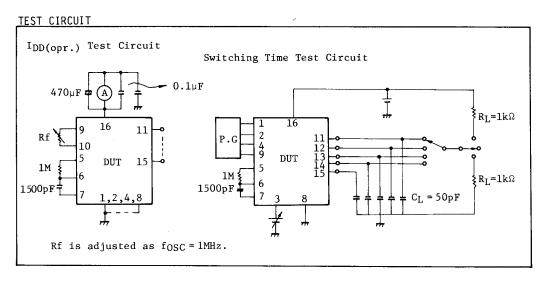
SWITCHING CHARACTERISTICS (VDD = 5V, VSS = 0V, Ta = 25°C, CL = 50 pF)

ITEM	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Output Rise Time	tTLH			50	100	
Output Fall Time	tTHL		-	40	100	
(Low-High) Propaga- tion Delay Time	tpLH	RSEL("L"→"H")-DATA OUT	-	180	400	
(High-Low) Propaga- tion Delay Time	tpHL	KSEL(L 7 H)-DATA OUT	-	150	400	
(Low-High) Propaga- tion Delay Time	tpLH	RSEL("H"→"L")-DATA OUT	-	380	700	
(High-Low) Propaga- tion Delay Time	tpHL	KSEL(II / L)-DATA OUT	_	300	700	ns
Output Enable Time	tZL tZH	RENB-DATA OUT	-	80	250	
Output Disable Time	tLZ tHZ	REND-DATA OUT	_	280	500	
Max. Clock Frequency	f MAXø	OSC Input	1.5	3.0	-	MHz
Min. Clock Frequency	fMINØ	OSC Input	-	-	100	kHz
Input Capacity	CIN	Digital Inputs	-	4	-	pF
Analog Input Capacity	CIN		-	7	_	pF
3-State Output Capacity	COUT		-	8	_	pF

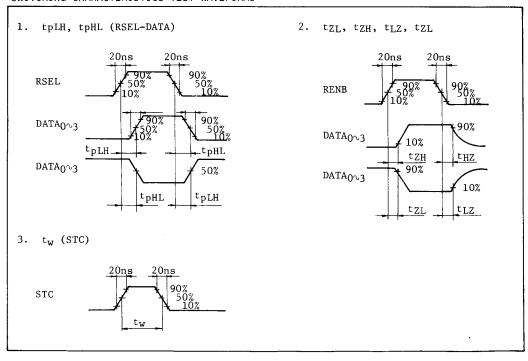
SYSTEM CHARACTERISTICS (Ta = $-40 \sim 85$ °C)

ITEM	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Zero Point Error	EZP		_	± 1/4	± 1/2	
Full Scale Error	EFS	V _{DD} =5V, V _{SS} =0V	-	± 1/4	±1	LSB
Nonlinearity			_	± 1/4	±1	
STC Min. Pulse Width	t _w	*	-	_	2 fosc	S
Conversion Time	t _{conv} .	$A_{IN} = 0 \sim FS$ *	10° fosc	_	3.1x10 ³ fosc	s

^{*} f_{OSC} : OSC terminal clock frequency [Hz], FS : Full Scale voltage, V_{DD} level



SWITCHING CHARACTERISTICS TEST WAVEFORMS



STANDARD CHARACTERISTICS CHARTS

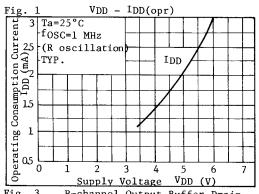
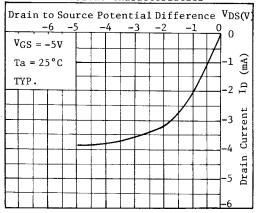
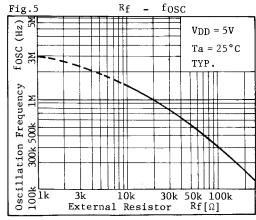


Fig. 3 P-channel Output Buffer Drain Current Characteristics





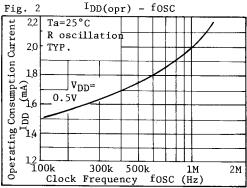
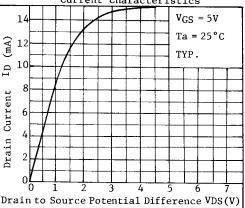
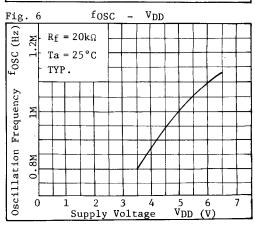


Fig. 4 N-channel Output Buffer Drain Current Characteristics





t_{pd} - V_{DD} (PENB-DATA) Fig. 7

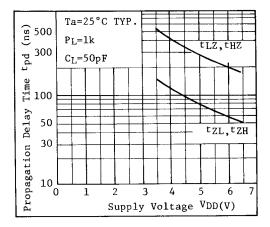


Fig. 8 tpd - VDD (RSEL (L→H)-DATA)

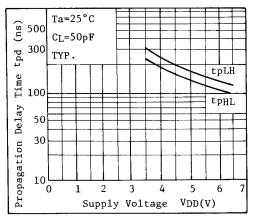
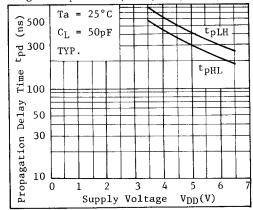
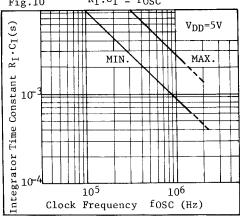


Fig. 9 $t_{pd} - V_{DD}(RSEL(H \rightarrow L) - DATA)$



R_I.C_I - fosc Fig.10



The characteristics at Fig. 10 have been prepared for reference at the (Note) time of determination of an integrator time constant, according to the for determing R $_{
m I} \cdot {
m C}_{
m I}$. equation of $(R_{I} \cdot C_{I} = (0.9 \cdot 2.5) \cdot \frac{10^{3}}{f_{osc}} [Sec])$

In case of the determination of R $_{
m I}$ and C $_{
m I}$, the product, or the value, of $R_{\rm I}$ and $C_{\rm I}$ is required to be within the range of MIN. to MAX. as shown in Fig. 10 after due consideration of dispersion.